



26th Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems

Important Dates

Abstract Deadline:	Sept. 28, 2026
Notification of Acceptance:	Oct. 26, 2026
Draft Paper Submission:	Jan. 4, 2027
Reviews Returned:	Feb. 8, 2027
Final Paper Submission:	Mar. 8, 2027

Jun 1 – 4, 2027

Gaylord Rockies
Resort & Convention Center
Denver, CO, USA



Call for Abstracts

The IEEE ITherm Conference is the leading international conference for scientific and engineering exploration of thermal, thermomechanical, and emerging technology issues associated with electronic devices, packages, and systems. ITherm 2027 will be an in-person conference held along with the 77th ECTC. Joint ITherm/ECTC registrations will be available at a substantial discount. All abstracts are followed by full papers to be peer reviewed and published in the IEEE Xplore ITherm proceedings. Student first authors will have the opportunity to apply for ITherm travel grants and participate in the Student Poster and Networking Session. ITherm 2027 will also feature keynote talks by prominent speakers, vendor exhibits, panel discussions, invited technology talks, ECTC/ITherm joint networking events and short courses, and a student design competition. Original papers are solicited in the following areas:

Component-Level Thermal Management

- Advanced Packaging/HI Thermal Management
- Heat Pipes, Vapor Chambers and Thermosyphons
- Hotspot and Impingement Cooling
- Micro-gaps and Embedded Cooling
- Multi-scale, Multi-physics and Reduced Order Modeling
- RF and Power Electronics
- Single / Two-Phase Cold Plates and Heat Sinks
- Thermal Interface Materials and Heat Spreaders
- Thermal Management of Electric Machines
- Thermoelectric and Peltier Devices

System-Level Thermal Management

- Advanced System Level Cooling Technologies
- Air Cooling Techniques and Heat Exchangers
- Aerospace Thermal Management
- Automotive, Batteries and Thermal Storage
- Cryogenics and Refrigeration
- Immersion Cooling
- Liquid Cooling Solutions
- System Integration and Optimization
- System Modeling and Digital Twins
- Transient Thermal Management

Mechanics and Reliability

- Accelerated Testing and Lifetime Modeling
- Advanced Packaging/HI Mechanics and Reliability
- Materials and Characterization
- Mechanics in Assembly and Manufacturing
- Measurement of Deformations, Strains, and Stresses
- Thermo-Mechanical Modeling and Simulation

Emerging Technologies and Fundamentals

- Additive Manufacturing and Topology Optimization
- Biomedical, Wearable, Flexible and Printed Electronics
- Boiling, Evaporation and Condensation
- Co-Packaged Optics, Near-Package Optics, and lasers
- Device/System Technology Co-Optimization and Co-Design
- Measurement and Diagnostic Techniques
- Nanoscale Thermal Transport
- Next Generation and Harsh Environment Electronics
- Novel Materials and Fabrication Techniques
- Packaging and Interconnect Technologies
- Predictive Analytics, Machine Learning and AI
- Quantum and Photonic Computing

Data Centers

- Air Cooling Methods
- Carbon Emissions and Sustainability
- Economics and Scaling
- Hybrid and Novel Cooling Methods
- Liquid Cooling Methods
- Modeling, AI/ML Techniques, Control and Optimization
- Performance Metrics, Standards and Regulatory Compliance
- Reliability and Failure Mitigation

ITherm provides an opportunity for industrial and university participation in the form of financial support to ITherm 2027. All contributors will be given strong recognition both onsite and in the conference materials.



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